

N-Channel Enhancement Mode MOSFET
◆ DESCRIPTION

The MT2306 is the N-Channel logic enhancement mode power field effect transistor are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance.

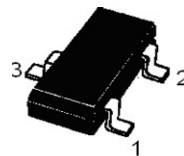
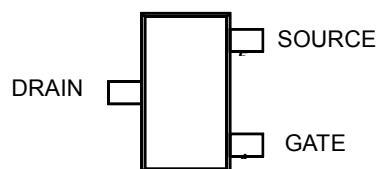
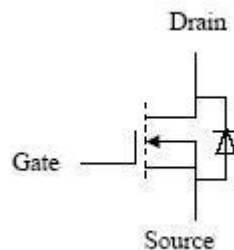
These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits, and low in-line power loss are needed in a very small outline surface mount package.

◆ FEATURES

- 30V/3.5A, $R_{DS(ON)} = 70 \text{ m}\Omega @ V_{GS} = 10. \text{V}$
- 30V/3.1A, $R_{DS(ON)} = 90 \text{ m}\Omega @ V_{GS} = 4.5 \text{V}$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- SOT-23-3L package design

◆ APPLICATIONS

- POWER Management in Note
- Portable Equipment
- Battery Powered System
- DC/DC Converter
- Load Switch
- DSC
- LCD Display inverter

◆ PIN CONFIGURATION


N-Channel Enhancement Mode MOSFET
◆ ABSOLUTE MAXIMUM RATINGS

 (T_A=25°C Unless Otherwise Noted)

Parameter	Symbol	Maximum	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current	I _D	T _A = 25°C	3.5
		T _A = 70°C	2.7
Pulsed Drain Current	I _{DM}	13	A
Continuous Source Current (Diode Conduction)	I _S	1.25	A
Power Dissipation	P _D	T _A = 25°C	1.25
		T _A = 70°C	0.8
Operating junction temperature range	T _J	150	°C
Storage temperature range	T _{STG}	- 55 to 150	°C

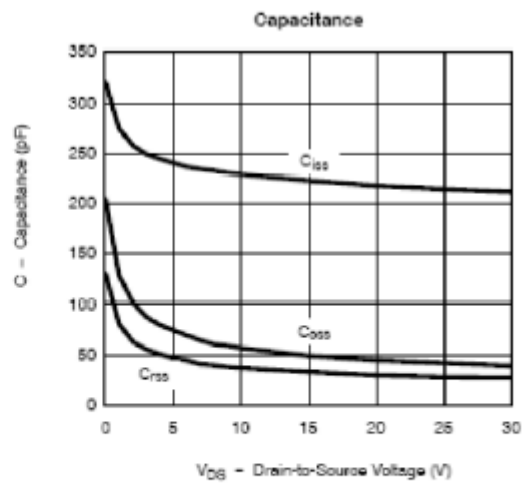
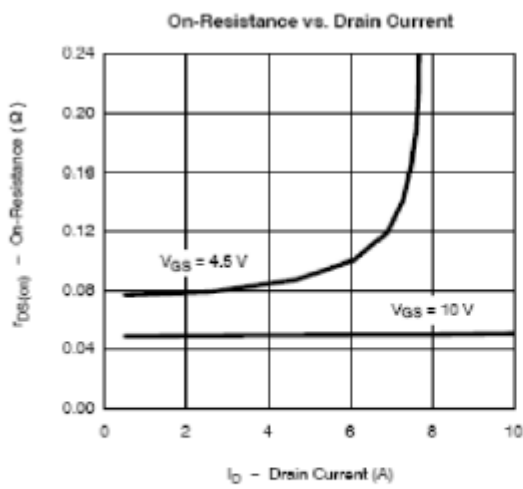
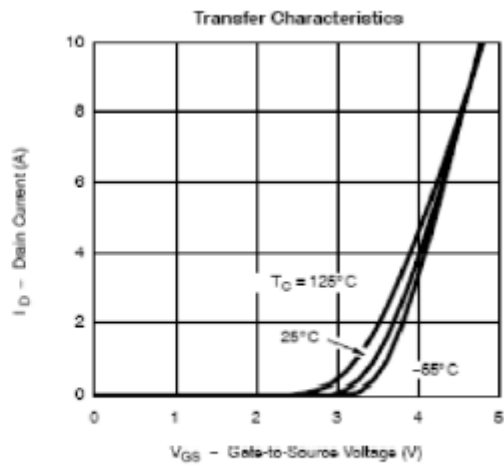
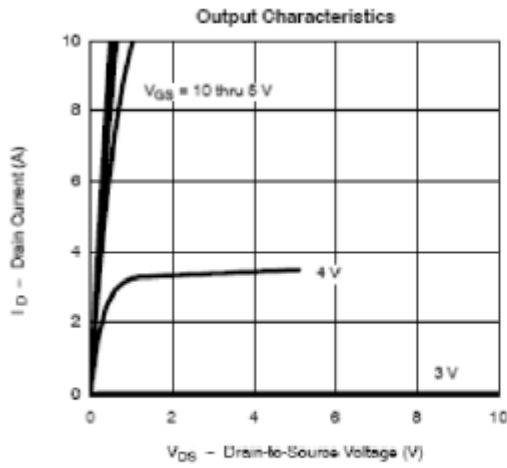
◆ THERMAL RESISTANCE RATINGS

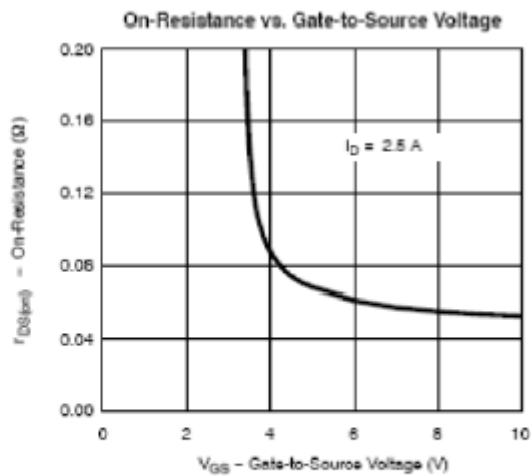
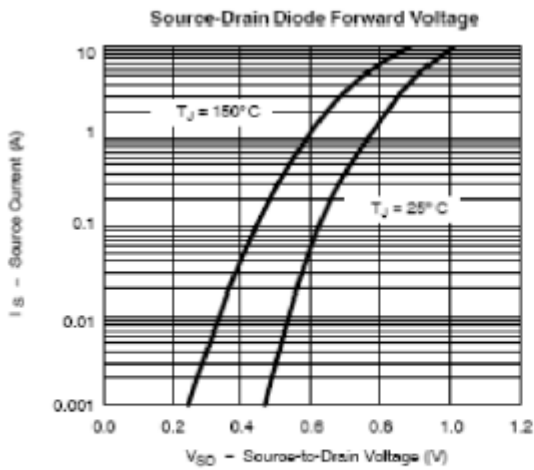
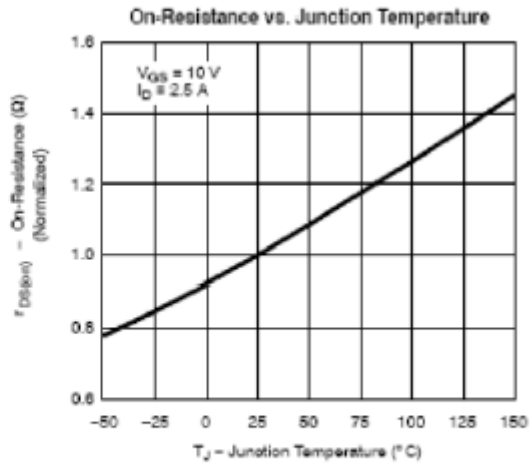
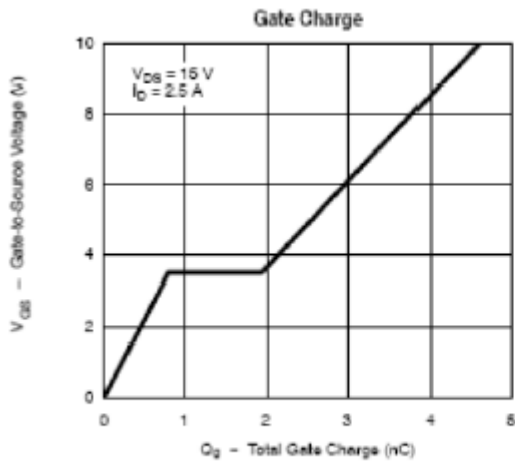
Parameter	Symbol	Maximum	Unit
Junction-to-Ambient	R _{θJA}	100	°C/W

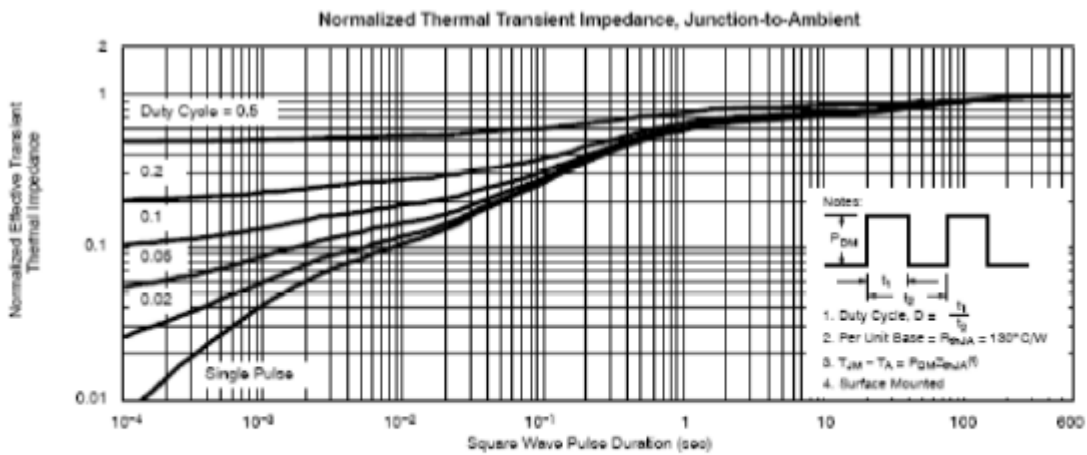
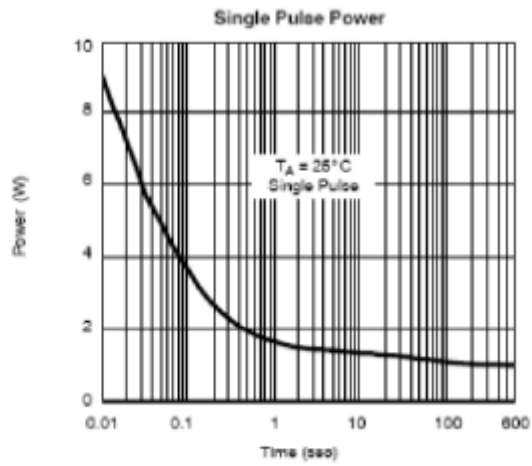
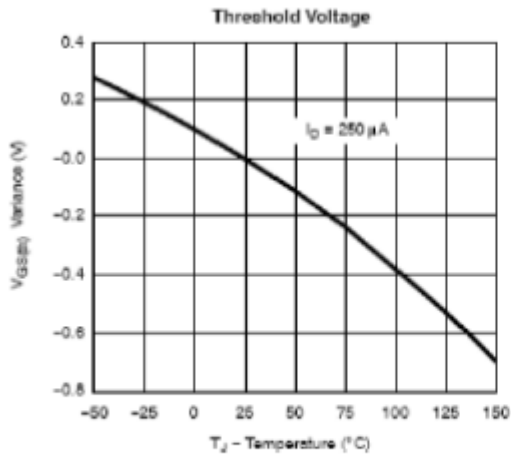
N-Channel Enhancement Mode MOSFET
◆ ELECTRICAL CHARACTERISTICS

 (T_A=25°C Unless Otherwise Noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Parameters						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250uA	30	-	-	V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	1.0	-	2.2	V
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V, V _{GS} =1.0V	-	-	1	μA
		V _{DS} =30V, V _{GS} =0V T _J =55°C	-	-	10	
Forward Trans conductance	g _{fs}	V _{DS} =4.5V, I _D =2.5V	-	4.6	-	S
On-State Drain Current	I _{D(ON)}	V _{DS} ≥ 4.5V, V _{GS} =10V	6	-	-	A
		V _{DS} ≥ 4.5V, V _{GS} =4.5V	4	-	-	
Drain-Source On Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =3.2A	-	50	65	mΩ
		V _{GS} =4.5V, I _D =2.0A	-	70	90	
		V _{GS} =2.5V, I _D =1.0A	-	1000	-	
Diode Forward Voltage	V _{SD}	I _S =1.25A, V _{GS} =0V	-	0.82	1.2	V
Dynamic						
Input Cap.	C _{iss}	V _{DS} =15V V _{GS} =0V F=1MHz	-	240	-	pF
Output Cap.	C _{oss}		-	110	-	
Reverse Transfer Cap.	C _{rss}		-	17	-	
Total Gate Charge	Q _g	V _{DS} =15V V _{GS} =10V I _D =2.5A	-	4.5	10	nC
Gate-Source Charge	Q _{gs}		-	0.8	-	
Gate-Drain Charge	Q _{gd}		-	1.0	-	
Turn-On Time	T _{D(ON)}	V _{DD} =15V R _L =15Ω I _D =1.0A V _{GEN} =10V R _G =6Ω	-	8	20	nS
	t _r		-	12	30	
Turn-Off Time	T _{D(OFF)}		-	17	35	
	T _f		-	8	20	

◆ TYPICAL CHARACTERISTICS


◆ TYPICAL CHARACTERISTICS


◆ TYPICAL CHARACTERISTICS


◆ PHYSICAL DIMENSIONS
3-Pin surface Mount SOT-23
